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## Features

### ■ High Performance

- $f_{MAX}$  = 400MHz maximum operating frequency
- $t_{PD}$  = 2.5ns propagation delay
- Up to four global clock pins with programmable clock polarity control
- Up to 80 PTs per output

### ■ Ease of Design

- Enhanced macrocells with individual clock, reset, preset and clock enable controls
- Up to four global OE controls
- Individual local OE control per I/O pin
- Excellent First-Time-Fit<sup>™</sup> and refit
- Fast path, SpeedLocking<sup>™</sup> Path, and wide-PT path
- Wide input gating (36 input logic blocks) for fast counters, state machines and address decoders

### ■ Zero Power (ispMACH 4000Z) and Low Power (ispMACH 4000V/B/C)

- Typical static current 10 $\mu$ A (4032Z)
- Typical static current 1.3mA (4000C)
- 1.8V core low dynamic power
- ispMACH 4000Z operational down to 1.6V  $V_{CC}$

### ■ Broad Device Offering

- Multiple temperature range support
  - Commercial: 0 to 90°C junction ( $T_j$ )
  - Industrial: -40 to 105°C junction ( $T_j$ )
  - Extended: -40 to 130°C junction ( $T_j$ )
- For AEC-Q100 compliant devices, refer to [LA-ispMACH 4000V/Z Automotive Data Sheet](#)

### ■ Easy System Integration

- Superior solution for power sensitive consumer applications
- Operation with 3.3V, 2.5V or 1.8V LVCMOS I/O
- Operation with 3.3V (4000V), 2.5V (4000B) or 1.8V (4000C/Z) supplies
- 5V tolerant I/O for LVCMOS 3.3, LVTTTL, and PCI interfaces
- Hot-socketing
- Open-drain capability
- Input pull-up, pull-down or bus-keeper
- Programmable output slew rate
- 3.3V PCI compatible
- IEEE 1149.1 boundary scan testable
- 3.3V/2.5V/1.8V In-System Programmable (ISP<sup>™</sup>) using IEEE 1532 compliant interface
- I/O pins with fast setup path
- Lead-free package options

**Table 1. ispMACH 4000V/B/C Family Selection Guide**

	ispMACH 4032V/B/C	ispMACH 4064V/B/C	ispMACH 4128V/B/C	ispMACH 4256V/B/C	ispMACH 4384V/B/C	ispMACH 4512V/B/C
Macrocells	32	64	128	256	384	512
I/O + Dedicated Inputs	30+2/32+4	30+2/32+4/ 64+10	64+10/92+4/ 96+4	64+10/96+14/ 128+4/160+4	128+4/192+4	128+4/208+4
$t_{PD}$ (ns)	2.5	2.5	2.7	3.0	3.5	3.5
$t_S$ (ns)	1.8	1.8	1.8	2.0	2.0	2.0
$t_{CO}$ (ns)	2.2	2.2	2.7	2.7	2.7	2.7
$f_{MAX}$ (MHz)	400	400	333	322	322	322
Supply Voltages (V)	3.3/2.5/1.8V	3.3/2.5/1.8V	3.3/2.5/1.8V	3.3/2.5/1.8V	3.3/2.5/1.8V	3.3/2.5/1.8V
Pins/Package	44 TQFP 48 TQFP	44 TQFP 48 TQFP 100 TQFP	100 TQFP 128 TQFP 144 TQFP <sup>1</sup>	100 TQFP  144 TQFP <sup>1</sup> 176 TQFP 256 ftBGA <sup>2</sup> / fpBGA <sup>2,3</sup>	176 TQFP 256 ftBGA/ fpBGA <sup>3</sup>	176 TQFP 256 ftBGA/ fpBGA <sup>3</sup>

1. 3.3V (4000V) only.

2. 128-I/O and 160-I/O configurations.

3. Use 256 ftBGA package for all new designs. Refer to PCN#14A-07 for 256 fpBGA package discontinuance.

**Table 2. ispMACH 4000Z Family Selection Guide**

	ispMACH 4032ZC	ispMACH 4064ZC	ispMACH 4128ZC	ispMACH 4256ZC
Macrocells	32	64	128	256
I/O + Dedicated Inputs	32+4/32+4	32+4/32+12/ 64+10/64+10	64+10/96+4	64+10/96+6/ 128+4
t <sub>PD</sub> (ns)	3.5	3.7	4.2	4.5
t <sub>S</sub> (ns)	2.2	2.5	2.7	2.9
t <sub>CO</sub> (ns)	3.0	3.2	3.5	3.8
f <sub>MAX</sub> (MHz)	267	250	220	200
Supply Voltage (V)	1.8	1.8	1.8	1.8
Max. Standby I <sub>CC</sub> (μA)	20	25	35	55
Pins/Package	48 TQFP 56 csBGA	48 TQFP 56 csBGA 100 TQFP 132 csBGA	100 TQFP 132csBGA	100 TQFP 132 csBGA 176 TQFP

## ispMACH 4000 Introduction

The high performance ispMACH 4000 family from Lattice offers a SuperFAST CPLD solution. The family is a blend of Lattice's two most popular architectures: the ispLSI® 2000 and ispMACH 4A. Retaining the best of both families, the ispMACH 4000 architecture focuses on significant innovations to combine the highest performance with low power in a flexible CPLD family.

The ispMACH 4000 combines high speed and low power with the flexibility needed for ease of design. With its robust Global Routing Pool and Output Routing Pool, this family delivers excellent First-Time-Fit, timing predictability, routing, pin-out retention and density migration.

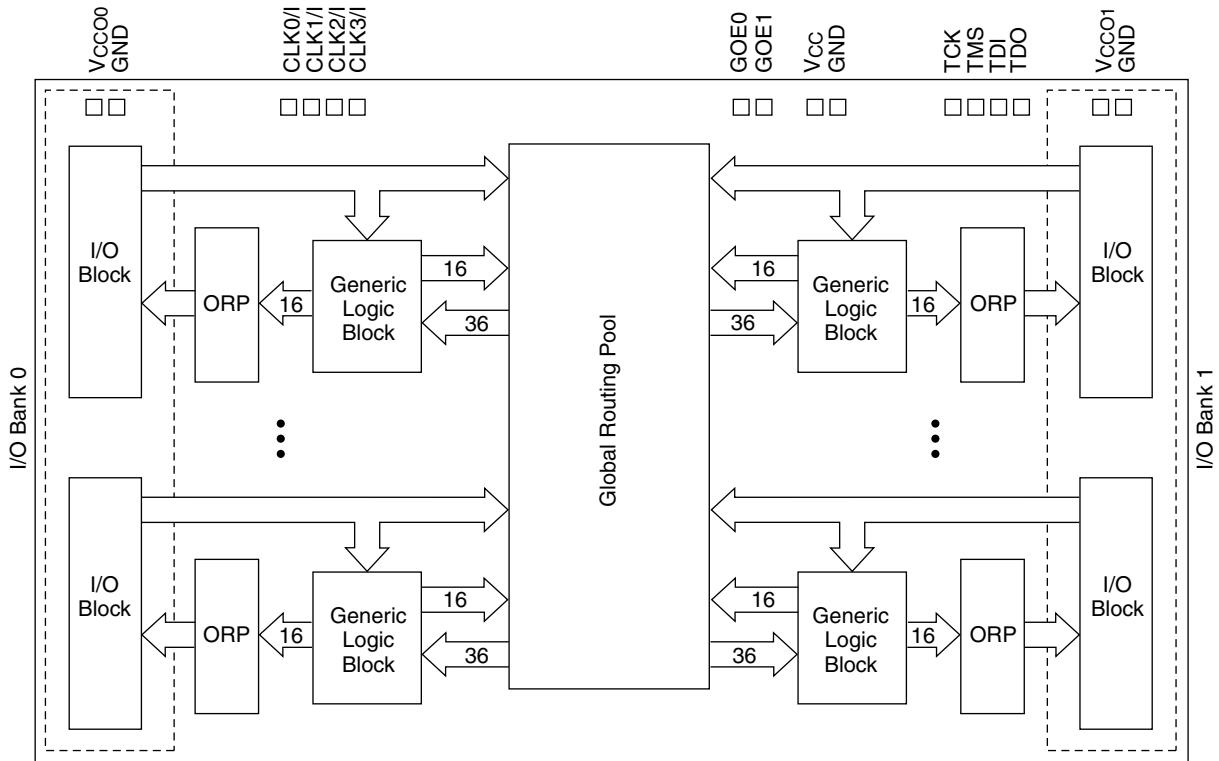
The ispMACH 4000 family offers densities ranging from 32 to 512 macrocells. There are multiple density-I/O combinations in Thin Quad Flat Pack (TQFP), Chip Scale BGA (csBGA) and Fine Pitch Thin BGA (ftBGA) packages ranging from 44 to 256 pins/balls. Table 1 shows the macrocell, package and I/O options, along with other key parameters.

The ispMACH 4000 family has enhanced system integration capabilities. It supports 3.3V (4000V), 2.5V (4000B) and 1.8V (4000C/Z) supply voltages and 3.3V, 2.5V and 1.8V interface voltages. Additionally, inputs can be safely driven up to 5.5V when an I/O bank is configured for 3.3V operation, making this family 5V tolerant. The ispMACH 4000 also offers enhanced I/O features such as slew rate control, PCI compatibility, bus-keeper latches, pull-up resistors, pull-down resistors, open drain outputs and hot socketing. The ispMACH 4000 family members are 3.3V/2.5V/1.8V in-system programmable through the IEEE Standard 1532 interface. IEEE Standard 1149.1 boundary scan testing capability also allows product testing on automated test equipment. The 1532 interface signals TCK, TMS, TDI and TDO are referenced to V<sub>CC</sub> (logic core).

## Overview

The ispMACH 4000 devices consist of multiple 36-input, 16-macrocell Generic Logic Blocks (GLBs) interconnected by a Global Routing Pool (GRP). Output Routing Pools (ORPs) connect the GLBs to the I/O Blocks (IOBs), which contain multiple I/O cells. This architecture is shown in Figure 1.

Figure 1. Functional Block Diagram



The I/Os in the ispMACH 4000 are split into two banks. Each bank has a separate I/O power supply. Inputs can support a variety of standards independent of the chip or bank power supply. Outputs support the standards compatible with the power supply provided to the bank. Support for a variety of standards helps designers implement designs in mixed voltage environments. In addition, 5V tolerant inputs are specified within an I/O bank that is connected to V<sub>CC0</sub> of 3.0V to 3.6V for LVCMOS 3.3, LVTTTL and PCI interfaces.

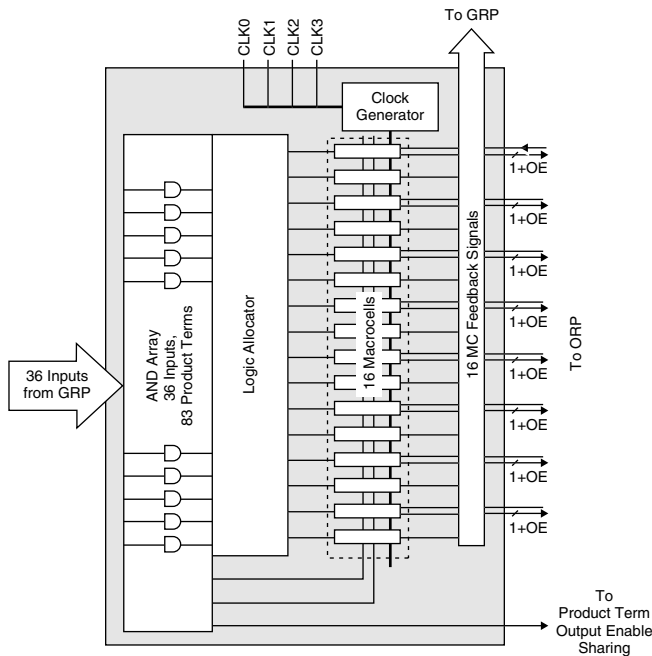
### ispMACH 4000 Architecture

There are a total of two GLBs in the ispMACH 4032, increasing to 32 GLBs in the ispMACH 4512. Each GLB has 36 inputs. All GLB inputs come from the GRP and all outputs from the GLB are brought back into the GRP to be connected to the inputs of any other GLB on the device. Even if feedback signals return to the same GLB, they still must go through the GRP. This mechanism ensures that GLBs communicate with each other with consistent and predictable delays. The outputs from the GLB are also sent to the ORP. The ORP then sends them to the associated I/O cells in the I/O block.

### Generic Logic Block

The ispMACH 4000 GLB consists of a programmable AND array, logic allocator, 16 macrocells and a GLB clock generator. Macrocells are decoupled from the product terms through the logic allocator and the I/O pins are decoupled from macrocells through the ORP. Figure 2 illustrates the GLB.

Figure 2. Generic Logic Block

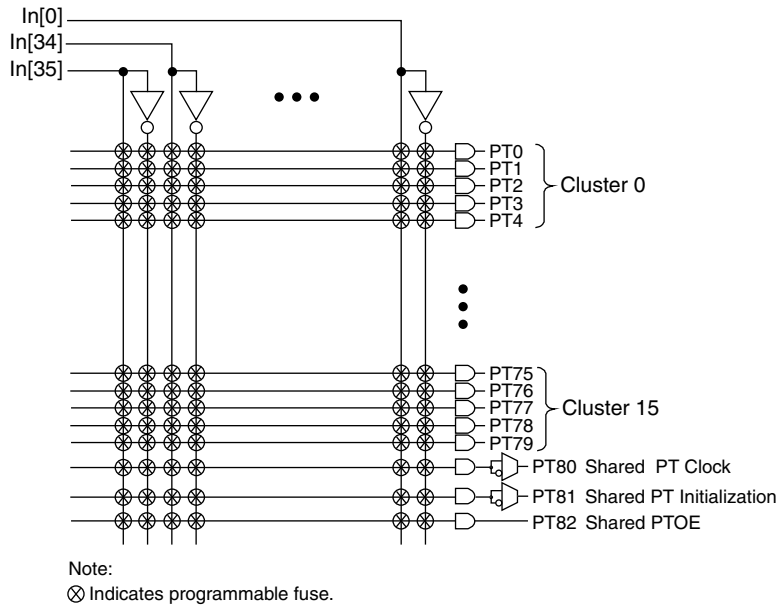


**AND Array**

The programmable AND Array consists of 36 inputs and 83 output product terms. The 36 inputs from the GRP are used to form 72 lines in the AND Array (true and complement of the inputs). Each line in the array can be connected to any of the 83 output product terms via a wired-AND. Each of the 80 logic product terms feed the logic allocator with the remaining three control product terms feeding the Shared PT Clock, Shared PT Initialization and Shared PT OE. The Shared PT Clock and Shared PT Initialization signals can optionally be inverted before being fed to the macrocells.

Every set of five product terms from the 80 logic product terms forms a product term cluster starting with PT0. There is one product term cluster for every macrocell in the GLB. Figure 3 is a graphical representation of the AND Array.

Figure 3. AND Array



### Enhanced Logic Allocator

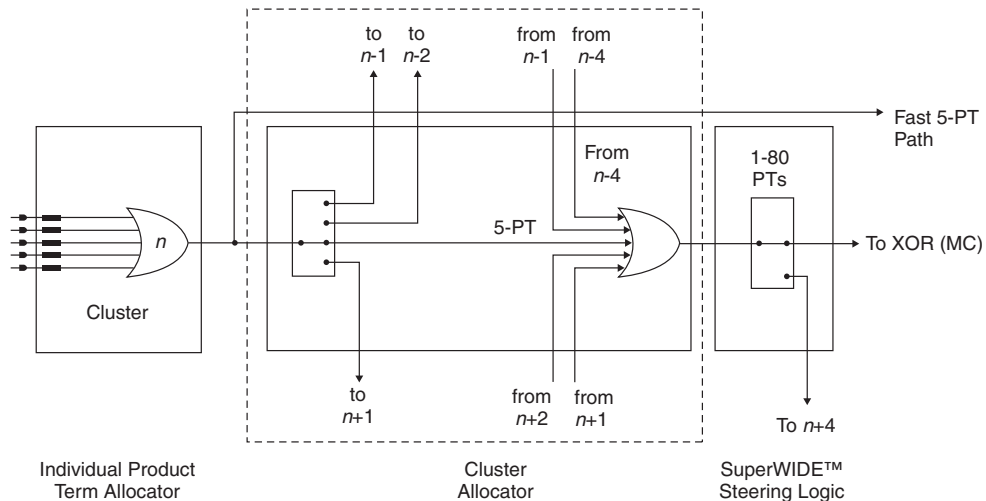
Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

Figure 4. Macrocell Slice



## Product Term Allocator

The product term allocator assigns product terms from a cluster to either logic or control applications as required by the design being implemented. Product terms that are used as logic are steered into a 5-input OR gate associated with the cluster. Product terms that used for control are steered either to the macrocell or I/O cell associated with the cluster. Table 3 shows the available functions for each of the five product terms in the cluster. The OR gate output connects to the associated I/O cell, providing a fast path for narrow combinatorial functions, and to the logic allocator.

**Table 3. Individual PT Steering**

Product Term	Logic	Control
PT $n$	Logic PT	Single PT for XOR/OR
PT $n+1$	Logic PT	Individual Clock (PT Clock)
PT $n+2$	Logic PT	Individual Initialization or Individual Clock Enable (PT Initialization/CE)
PT $n+3$	Logic PT	Individual Initialization (PT Initialization)
PT $n+4$	Logic PT	Individual OE (PTOE)

## Cluster Allocator

The cluster allocator allows clusters to be steered to neighboring macrocells, thus allowing the creation of functions with more product terms. Table 4 shows which clusters can be steered to which macrocells. Used in this manner, the cluster allocator can be used to form functions of up to 20 product terms. Additionally, the cluster allocator accepts inputs from the wide steering logic. Using these inputs, functions up to 80 product terms can be created.

**Table 4. Available Clusters for Each Macrocell**

Macrocell	Available Clusters			
M0	—	C0	C1	C2
M1	C0	C1	C2	C3
M2	C1	C2	C3	C4
M3	C2	C3	C4	C5
M4	C3	C4	C5	C6
M5	C4	C5	C6	C7
M6	C5	C6	C7	C8
M7	C6	C7	C8	C9
M8	C7	C8	C9	C10
M9	C8	C9	C10	C11
M10	C9	C10	C11	C12
M11	C10	C11	C12	C13
M12	C11	C12	C13	C14
M13	C12	C13	C14	C15
M14	C13	C14	C15	—
M15	C14	C15	—	—

## Wide Steering Logic

The wide steering logic allows the output of the cluster allocator  $n$  to be connected to the input of the cluster allocator  $n+4$ . Thus, cluster chains can be formed with up to 80 product terms, supporting wide product term functions and allowing performance to be increased through a single GLB implementation. Table 5 shows the product term chains.

**Table 5. Product Term Expansion Capability**

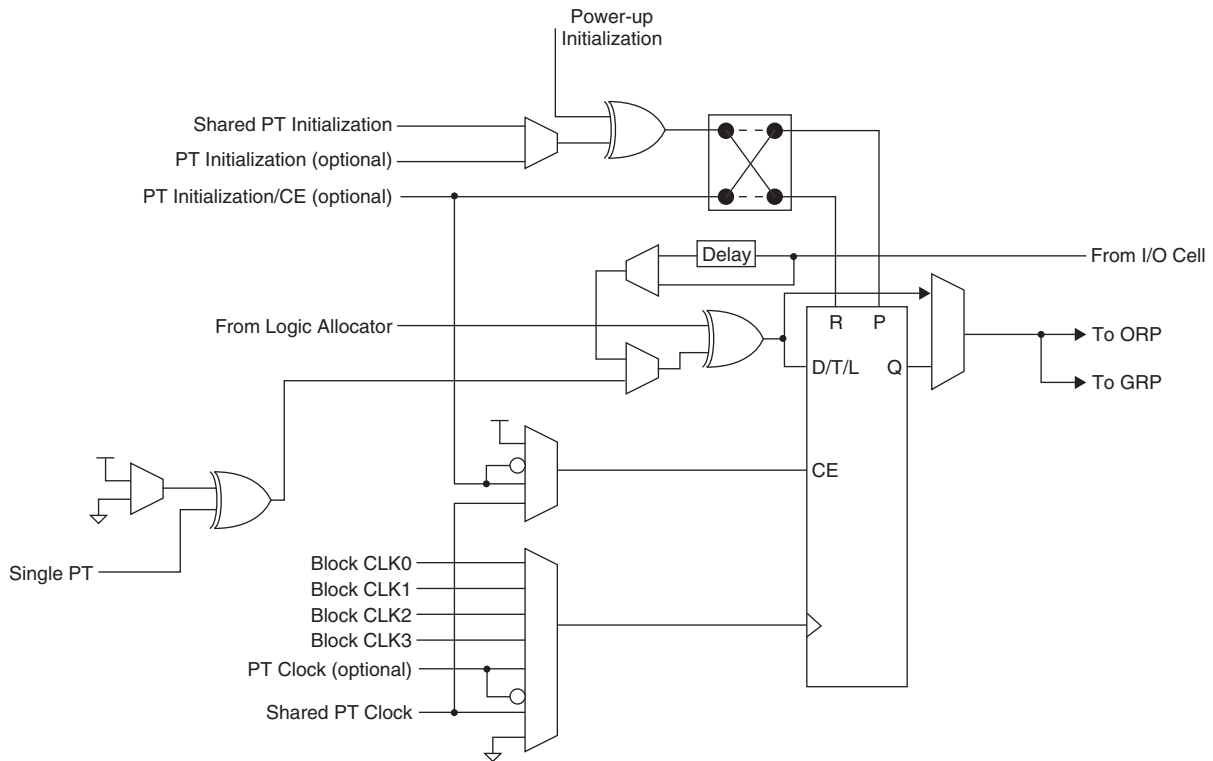
Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of  $t_{EXP}$ . When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

**Macrocell**

The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

**Figure 5. Macrocell**



**Enhanced Clock Multiplexer**

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1



- Block CLK2
- Block CLK3
- PT Clock
- PT Clock Inverted
- Shared PT Clock
- Ground

### Clock Enable Multiplexer

Each macrocell has a 4:1 clock enable multiplexer. This allows the clock enable signal to be selected from the following four sources:

- PT Initialization/CE
- PT Initialization/CE Inverted
- Shared PT Clock
- Logic High

### Initialization Control

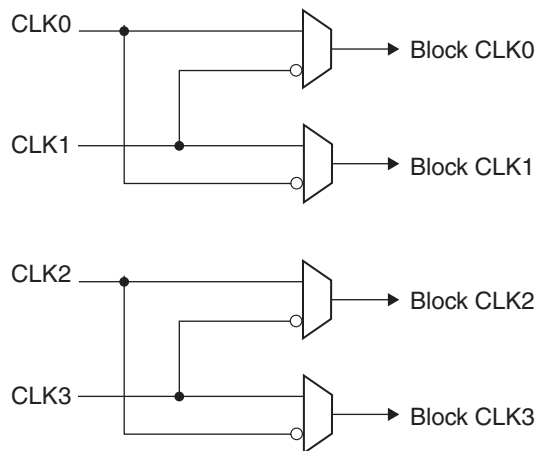
The ispMACH 4000 family architecture accommodates both block-level and macrocell-level set and reset capability. There is one block-level initialization term that is distributed to all macrocell registers in a GLB. At the macrocell level, two product terms can be “stolen” from the cluster associated with a macrocell to be used for set/reset functionality. A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility.

Note that the reset/preset swapping selection feature affects power-up reset as well. All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the block-level initialization, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the block-level initialization or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the  $V_{CC}$  rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

### GLB Clock Generator

Each ispMACH 4000 device has up to four clock pins that are also routed to the GRP to be used as inputs. These pins drive a clock generator in each GLB, as shown in Figure 6. The clock generator provides four clock signals that can be used anywhere in the GLB. These four GLB clock signals can consist of a number of combinations of the true and complement edges of the global clock signals.

**Figure 6. GLB Clock Generator**



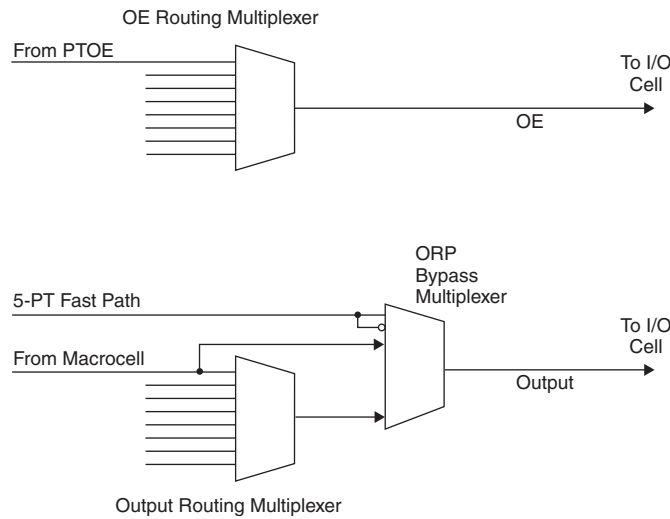
### Output Routing Pool (ORP)

The Output Routing Pool allows macrocell outputs to be connected to any of several I/O cells within an I/O block. This provides greater flexibility in determining the pinout and allows design changes to occur without affecting the pinout. The output routing pool also provides a parallel capability for routing macrocell-level OE product terms. This allows the OE product term to follow the macrocell output as it is switched between I/O cells. Additionally, the output routing pool allows the macrocell output or true and complement forms of the 5-PT bypass signal to bypass the output routing multiplexers and feed the I/O cell directly. The enhanced ORP of the ispMACH 4000 family consists of the following elements:

- Output Routing Multiplexers
- OE Routing Multiplexers
- Output Routing Pool Bypass Multiplexers

Figure 7 shows the structure of the ORP from the I/O cell perspective. This is referred to as an ORP slice. Each ORP has as many ORP slices as there are I/O cells in the corresponding I/O block.

**Figure 7. ORP Slice**



### Output Routing Multiplexers

The details of connections between the macrocells and the I/O cells vary across devices and within a device dependent on the maximum number of I/Os available. Tables 5-9 provide the connection details.

**Table 6. ORP Combinations for I/O Blocks with 8 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5

**Table 7. ORP Combinations for I/O Blocks with 16 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M3, M4, M5, M6, M7, M8, M9, M10
I/O 4	M4, M5, M6, M7, M8, M9, M10, M11
I/O 5	M5, M6, M7, M8, M9, M10, M11, M12
I/O 6	M6, M7, M8, M9, M10, M11, M12, M13
I/O 7	M7, M8, M9, M10, M11, M12, M13, M14
I/O 8	M8, M9, M10, M11, M12, M13, M14, M15
I/O 9	M9, M10, M11, M12, M13, M14, M15, M0
I/O 10	M10, M11, M12, M13, M14, M15, M0, M1
I/O 11	M11, M12, M13, M14, M15, M0, M1, M2
I/O 12	M12, M13, M14, M15, M0, M1, M2, M3
I/O 13	M13, M14, M15, M0, M1, M2, M3, M4
I/O 14	M14, M15, M0, M1, M2, M3, M4, M5
I/O 15	M15, M0, M1, M2, M3, M4, M5, M6

**Table 8. ORP Combinations for I/O Blocks with 4 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M4, M5, M6, M7, M8, M9, M10, M11
I/O 2	M8, M9, M10, M11, M12, M13, M14, M15
I/O 3	M12, M13, M14, M15, M0, M1, M2, M3

**Table 9. ORP Combinations for I/O Blocks with 10 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M2, M3, M4, M5, M6, M7, M8, M9
I/O 2	M4, M5, M6, M7, M8, M9, M10, M11
I/O 3	M6, M7, M8, M9, M10, M11, M12, M13
I/O 4	M8, M9, M10, M11, M12, M13, M14, M15
I/O 5	M10, M11, M12, M13, M14, M15, M0, M1
I/O 6	M12, M13, M14, M15, M0, M1, M2, M3
I/O 7	M14, M15, M0, M1, M2, M3, M4, M5
I/O 8	M2, M3, M4, M5, M6, M7, M8, M9
I/O 9	M10, M11, M12, M13, M14, M15, M0, M1

**Table 10. ORP Combinations for I/O Blocks with 12 I/Os**

I/O Cell	Available Macrocells
I/O 0	M0, M1, M2, M3, M4, M5, M6, M7
I/O 1	M1, M2, M3, M4, M5, M6, M7, M8
I/O 2	M2, M3, M4, M5, M6, M7, M8, M9
I/O 3	M4, M5, M6, M7, M8, M9, M10, M11
I/O 4	M5, M6, M7, M8, M9, M10, M11, M12
I/O 5	M6, M7, M8, M9, M10, M11, M12, M13
I/O 6	M8, M9, M10, M11, M12, M13, M14, M15
I/O 7	M9, M10, M11, M12, M13, M14, M15, M0
I/O 8	M10, M11, M12, M13, M14, M15, M0, M1
I/O 9	M12, M13, M14, M15, M0, M1, M2, M3
I/O 10	M13, M14, M15, M0, M1, M2, M3, M4
I/O 11	M14, M15, M0, M1, M2, M3, M4, M5

**ORP Bypass and Fast Output Multiplexers**

The ORP bypass and fast-path output multiplexer is a 4:1 multiplexer and allows the 5-PT fast path to bypass the ORP and be connected directly to the pin with either the regular output or the inverted output. This multiplexer also allows the register output to bypass the ORP to achieve faster  $t_{CO}$ .

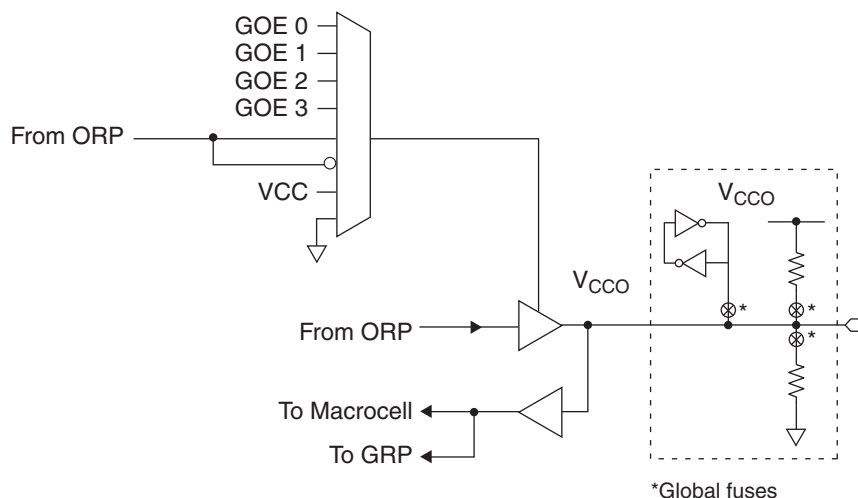
**Output Enable Routing Multiplexers**

The OE Routing Pool provides the corresponding local output enable (OE) product term to the I/O cell.

**I/O Cell**

The I/O cell contains the following programmable elements: output buffer, input buffer, OE multiplexer and bus maintenance circuitry. Figure 8 details the I/O cell.

**Figure 8. I/O Cell**



Each output supports a variety of output standards dependent on the  $V_{CCO}$  supplied to its I/O bank. Outputs can also be configured for open drain operation. Each input can be programmed to support a variety of standards, independent of the  $V_{CCO}$  supplied to its I/O bank. The I/O standards supported are:

- LVTTTL
- LVC MOS 3.3
- LVC MOS 2.5
- LVC MOS 1.8
- 3.3V PCI Compatible

All of the I/Os and dedicated inputs have the capability to provide a bus-keeper latch, Pull-up Resistor or Pull-down Resistor. A fourth option is to provide none of these. The selection is done on a global basis. The default in both hardware and software is such that when the device is erased or if the user does not specify, the input structure is configured to be a Pull-up Resistor.

Each ispMACH 4000 device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for fast slew or slow slew. The typical edge rate difference between fast and slow slew setting is 20%. For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed.

### Global OE Generation

Most ispMACH 4000 family devices have a 4-bit wide Global OE Bus, except the ispMACH 4032 device that has a 2-bit wide Global OE Bus. This bus is derived from a 4-bit internal global OE PT bus and two dual purpose I/O or GOE pins. Each signal that drives the bus can optionally be inverted.

Each GLB has a block-level OE PT that connects to all bits of the Global OE PT bus with four fuses. Hence, for a 256-macrocell device (with 16 blocks), each line of the bus is driven from 16 OE product terms. Figures 9 and 10 show a graphical representation of the global OE generation.

**Figure 9. Global OE Generation for All Devices Except ispMACH 4032**

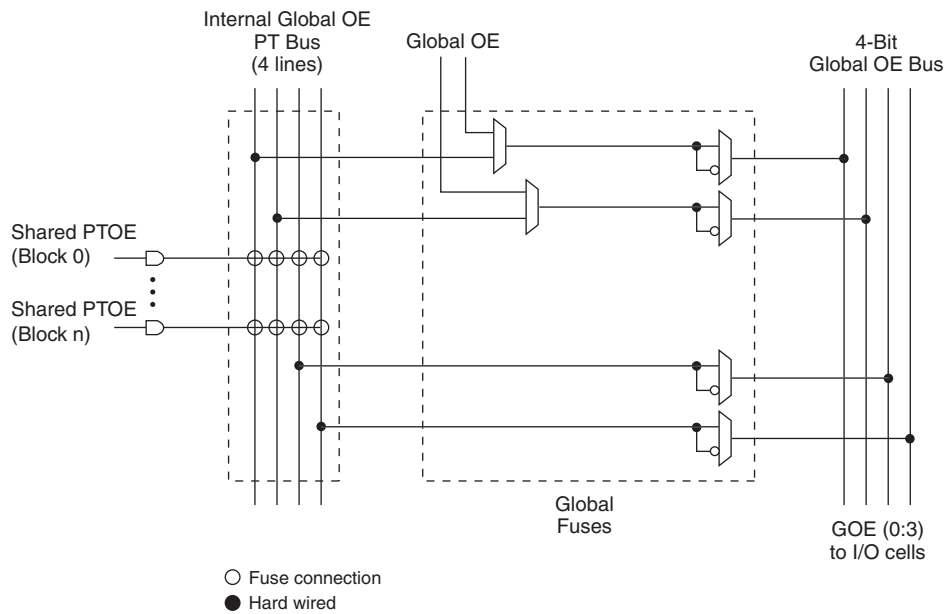
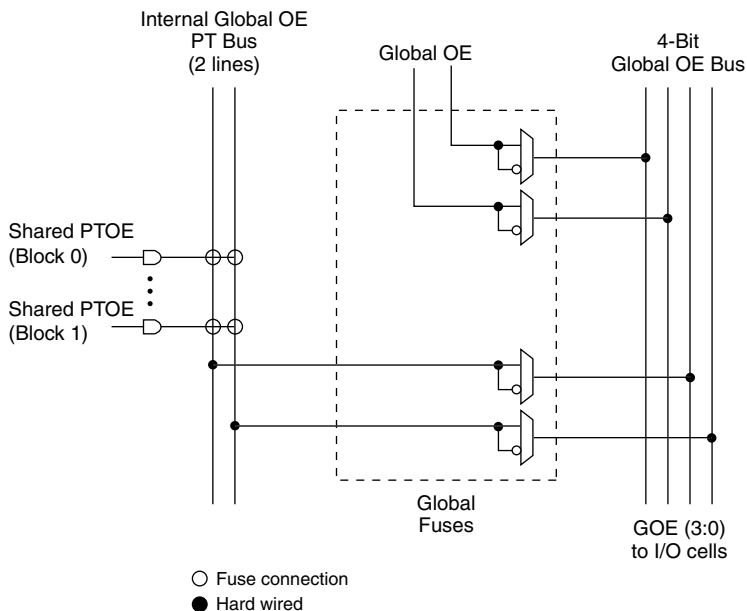


Figure 10. Global OE Generation for ispMACH 4032



## Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E<sup>2</sup> low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

## IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

## I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice’s ispVM<sup>®</sup> System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

## IEEE 1532-Compliant In-System Programming

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispMACH 4000 devices provide In-System Programming (ISP™) capability through the Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, users get the benefit of a standard, well-defined interface. All ispMACH 4000 devices are also compliant with the IEEE 1532 standard.

The ispMACH 4000 devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispMACH 4000 devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4000 devices during the testing of a circuit board.

## User Electronic Signature

The User Electronic Signature (UES) allows the designer to include identification bits or serial numbers inside the device, stored in E<sup>2</sup>CMOS memory. The ispMACH 4000 device contains 32 UES bits that can be configured by the user to store unique data such as ID codes, revision numbers or inventory control codes.

## Security Bit

A programmable security bit is provided on the ispMACH 4000 devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

## Hot Socketing

The ispMACH 4000 devices are well-suited for applications that require hot socketing capability. Hot socketing a device requires that the device, during power-up and down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of I/O pin loading be minimal on active signals. The ispMACH 4000 devices provide this capability for input voltages in the range 0V to 3.0V.

## Density Migration

The ispMACH 4000 family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

### Absolute Maximum Ratings<sup>1, 2, 3</sup>

	ispMACH 4000C/Z (1.8V)	ispMACH 4000B (2.5V)	ispMACH 4000V (3.3V)
Supply Voltage (V <sub>CC</sub> )	-0.5 to 2.5V	-0.5 to 5.5V	-0.5 to 5.5V
Output Supply Voltage (V <sub>CCO</sub> )	-0.5 to 4.5V	-0.5 to 4.5V	-0.5 to 4.5V
Input or I/O Tristate Voltage Applied <sup>4, 5</sup>	-0.5 to 5.5V	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C	-65 to 150°C
Junction Temperature (T <sub>j</sub> ) with Power Applied	-55 to 150°C	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.
2. Compliance with Lattice [Thermal Management](#) document is required.
3. All voltages referenced to GND.
4. Undershoot of -2V and overshoot of (V<sub>IH</sub> (MAX) + 2V), up to a total pin voltage of 6.0V, is permitted for a duration of < 20ns.
5. Maximum of 64 I/Os per device with V<sub>IN</sub> > 3.6V is allowed.

### Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units	
V <sub>CC</sub>	Supply Voltage for 1.8V Devices	ispMACH 4000C	1.65	1.95	V
		ispMACH 4000Z	1.7	1.9	V
		ispMACH 4000Z, Extended Functional Voltage Operation	1.6 <sup>1, 2</sup>	1.9	V
	Supply Voltage for 2.5V Devices	2.3	2.7	V	
	Supply Voltage for 3.3V Devices	3.0	3.6	V	
T <sub>j</sub>	Junction Temperature (Commercial)	0	90	C	
	Junction Temperature (Industrial)	-40	105	C	
	Junction Temperature (Extended)	-40	130	C	

1. Devices operating at 1.6V can expect performance degradation up to 35%.
2. Applicable for devices with 2004 date codes and later. Contact factory for ordering instructions.

### Erase Reprogram Specifications

Parameter	Min.	Max.	Units
Erase/Reprogram Cycle	1,000	—	Cycles

Note: Valid over commercial temperature range.

### Hot Socketing Characteristics<sup>1,2,3</sup>

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I <sub>DK</sub>	Input or I/O Leakage Current	0 ≤ V <sub>IN</sub> ≤ 3.0V, T <sub>j</sub> = 105°C	—	±30	±150	μA
		0 ≤ V <sub>IN</sub> ≤ 3.0V, T <sub>j</sub> = 130°C	—	±30	±200	μA

1. Insensitive to sequence of V<sub>CC</sub> or V<sub>CCO</sub>. However, assumes monotonic rise/fall rates for V<sub>CC</sub> and V<sub>CCO</sub>, provided (V<sub>IN</sub> - V<sub>CCO</sub>) ≤ 3.6V.
2. 0 < V<sub>CC</sub> < V<sub>CC</sub> (MAX), 0 < V<sub>CCO</sub> < V<sub>CCO</sub> (MAX).
3. I<sub>DK</sub> is additive to I<sub>PU</sub>, I<sub>PD</sub> or I<sub>BH</sub>. Device defaults to pull-up until fuse circuitry is active.



## I/O Recommended Operating Conditions

Standard	$V_{CCO}$ (V) <sup>1</sup>	
	Min.	Max.
LVTTTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 <sup>2</sup>	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for  $V_{CCO}$  are the average of the min. and max. values.

2. ispMACH 4000Z only.

## DC Electrical Characteristics

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	$\mu A$
$I_{IH}^1$	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	$\mu A$
$I_{IL}, I_{IH}^1$	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$	—	—	10	$\mu A$
		$0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	15	$\mu A$
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	20	$\mu A$
		$3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V$	—	—	50	$\mu A$
$I_{PU}$	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	$\mu A$
	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	$\mu A$
$I_{PD}$	I/O Weak Pull-down Resistor Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MIN)$	30	—	150	$\mu A$
$I_{BHLS}$	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	$\mu A$
$I_{BHHS}$	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	$\mu A$
$I_{BHLO}$	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	$\mu A$
$I_{BHHO}$	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	$\mu A$
$V_{BHT}$	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
$C_1$	I/O Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	
$C_2$	Clock Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	
$C_3$	Global Input Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where  $3.0V \leq V_{CCO} \leq 3.6V$ .

3.  $T_A = 25^\circ C, f = 1.0MHz$

4.  $I_{IH}$  excursions of up to 1.5 $\mu A$  maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

## Supply Current, ispMACH 4000V/B/C

## Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4032V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.8	—	mA
		V <sub>CC</sub> = 2.5V	—	11.8	—	mA
		V <sub>CC</sub> = 1.8V	—	1.8	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.3	—	mA
		V <sub>CC</sub> = 2.5V	—	11.3	—	mA
		V <sub>CC</sub> = 1.8V	—	1.3	—	mA
<b>ispMACH 4064V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	12	—	mA
		V <sub>CC</sub> = 2.5V	—	12	—	mA
		V <sub>CC</sub> = 1.8V	—	2	—	mA
ICC <sup>5</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.5	—	mA
		V <sub>CC</sub> = 2.5V	—	11.5	—	mA
		V <sub>CC</sub> = 1.8V	—	1.5	—	mA
<b>ispMACH 4128V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	12	—	mA
		V <sub>CC</sub> = 2.5V	—	12	—	mA
		V <sub>CC</sub> = 1.8V	—	2	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.5	—	mA
		V <sub>CC</sub> = 2.5V	—	11.5	—	mA
		V <sub>CC</sub> = 1.8V	—	1.5	—	mA
<b>ispMACH 4256V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	12.5	—	mA
		V <sub>CC</sub> = 2.5V	—	12.5	—	mA
		V <sub>CC</sub> = 1.8V	—	2.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	12	—	mA
		V <sub>CC</sub> = 2.5V	—	12	—	mA
		V <sub>CC</sub> = 1.8V	—	2	—	mA
<b>ispMACH 4384V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	13.5	—	mA
		V <sub>CC</sub> = 2.5V	—	13.5	—	mA
		V <sub>CC</sub> = 1.8V	—	3.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	12.5	—	mA
		V <sub>CC</sub> = 2.5V	—	12.5	—	mA
		V <sub>CC</sub> = 1.8V	—	2.5	—	mA
<b>ispMACH 4512V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	14	—	mA
		V <sub>CC</sub> = 2.5V	—	14	—	mA
		V <sub>CC</sub> = 1.8V	—	4	—	mA

## Supply Current, ispMACH 4000V/B/C (Cont.)

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{CC}^4$	Standby Power Supply Current	$V_{CC} = 3.3V$	—	13	—	mA
		$V_{CC} = 2.5V$	—	13	—	mA
		$V_{CC} = 1.8V$	—	3	—	mA

1.  $T_A = 25^\circ C$ , frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3.  $I_{CC}$  varies with specific device configuration and operating frequency.
4.  $T_A = 25^\circ C$

## Supply Current, ispMACH 4000Z

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4032ZC</b>						
$ICC^{1,2,3,5}$	Operating Power Supply Current	$V_{CC} = 1.8V, T_A = 25^\circ C$	—	50	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 70^\circ C$	—	58	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 85^\circ C$	—	60	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 125^\circ C$	—	70	—	$\mu A$
$ICC^{4,5}$	Standby Power Supply Current	$V_{CC} = 1.8V, T_A = 25^\circ C$	—	10	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 70^\circ C$	—	13	20	$\mu A$
		$V_{CC} = 1.9V, T_A = 85^\circ C$	—	15	25	$\mu A$
		$V_{CC} = 1.9V, T_A = 125^\circ C$	—	22	—	$\mu A$
<b>ispMACH 4064ZC</b>						
$ICC^{1,2,3,5}$	Operating Power Supply Current	$V_{CC} = 1.8V, T_A = 25^\circ C$	—	80	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 70^\circ C$	—	89	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 85^\circ C$	—	92	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 125^\circ C$	—	109	—	$\mu A$
$ICC^{4,5}$	Standby Power Supply Current	$V_{CC} = 1.8V, T_A = 25^\circ C$	—	11	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 70^\circ C$	—	15	25	$\mu A$
		$V_{CC} = 1.9V, T_A = 85^\circ C$	—	18	35	$\mu A$
		$V_{CC} = 1.9V, T_A = 125^\circ C$	—	37	—	$\mu A$
<b>ispMACH 4128ZC</b>						
$ICC^{1,2,3,5}$	Operating Power Supply Current	$V_{CC} = 1.8V, T_A = 25^\circ C$	—	168	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 70^\circ C$	—	190	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 85^\circ C$	—	195	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 125^\circ C$	—	212	—	$\mu A$
$ICC^{4,5}$	Standby Power Supply Current	$V_{CC} = 1.8V, T_A = 25^\circ C$	—	12	—	$\mu A$
		$V_{CC} = 1.9V, T_A = 70^\circ C$	—	16	35	$\mu A$
		$V_{CC} = 1.9V, T_A = 85^\circ C$	—	19	50	$\mu A$
		$V_{CC} = 1.9V, T_A = 125^\circ C$	—	42	—	$\mu A$

**Supply Current, ispMACH 4000Z (Cont.)**

**Over Recommended Operating Conditions**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4256ZC</b>						
ICC <sup>1,2,3,5</sup>	Operating Power Supply Current	V <sub>CC</sub> = 1.8V, T <sub>A</sub> = 25°C	—	341	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 70°C	—	361	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 85°C	—	372	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 125°C	—	468	—	μA
ICC <sup>4,5</sup>	Standby Power Supply Current	V <sub>CC</sub> = 1.8V, T <sub>A</sub> = 25°C	—	13	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 70°C	—	32	55	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 85°C	—	43	90	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 125°C	—	135	—	μA

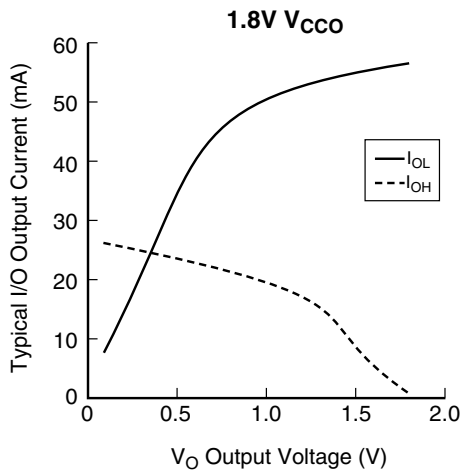
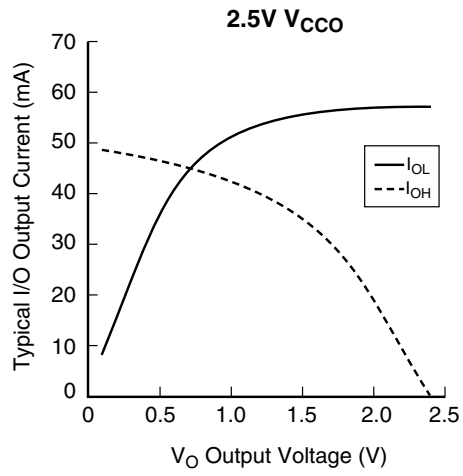
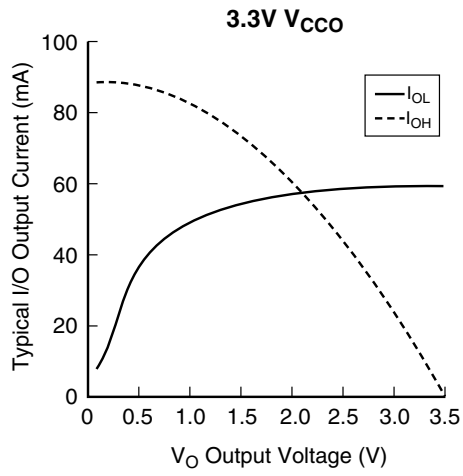
1. T<sub>A</sub> = 25°C, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I<sub>CC</sub> varies with specific device configuration and operating frequency.
4. V<sub>CCO</sub> = 3.6V, V<sub>IN</sub> = 0V or V<sub>CCO</sub>, bus maintenance turned off. V<sub>IN</sub> above V<sub>CCO</sub> will add transient current above the specified standby I<sub>CC</sub>.
5. Includes V<sub>CCO</sub> current without output loading.

**I/O DC Electrical Characteristics**

**Over Recommended Operating Conditions**

Standard	V <sub>IL</sub>		V <sub>IH</sub>		V <sub>OL</sub> Max (V)	V <sub>OH</sub> Min (V)	I <sub>OL</sub> <sup>1</sup> (mA)	I <sub>OH</sub> <sup>1</sup> (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTTL	-0.3	0.80	2.0	5.5	0.40	V <sub>CCO</sub> - 0.40	8.0	-4.0
					0.20	V <sub>CCO</sub> - 0.20	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	V <sub>CCO</sub> - 0.40	8.0	-4.0
					0.20	V <sub>CCO</sub> - 0.20	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	V <sub>CCO</sub> - 0.40	8.0	-4.0
					0.20	V <sub>CCO</sub> - 0.20	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	V <sub>CCO</sub> - 0.45	2.0	-2.0
					0.20	V <sub>CCO</sub> - 0.20	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	0.35 * V <sub>CC</sub>	0.65 * V <sub>CC</sub>	3.6	0.40	V <sub>CCO</sub> - 0.45	2.0	-2.0
					0.20	V <sub>CCO</sub> - 0.20	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	0.1 V <sub>CCO</sub>	0.9 V <sub>CCO</sub>	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	0.3 * 3.3 * (V <sub>CC</sub> / 1.8)	0.5 * 3.3 * (V <sub>CC</sub> / 1.8)	5.5	0.1 V <sub>CCO</sub>	0.9 V <sub>CCO</sub>	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed  $n \cdot 8\text{mA}$ . Where  $n$  is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.



## ispMACH 4000V/B/C External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description <sup>1, 2, 3</sup>	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t <sub>PD_MC</sub>	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t <sub>S</sub>	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t <sub>R</sub>	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t <sub>RW</sub>	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t <sub>P<sub>TOE/DIS</sub></sub>	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t <sub>G<sub>P<sub>TOE/DIS</sub></sub></sub>	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t <sub>G<sub>OE/DIS</sub></sub>	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t <sub>CW</sub>	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f <sub>MAX</sub> (Ext.)	Clock frequency with external feedback, [1/ (t <sub>S</sub> + t <sub>CO</sub> )]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

## ispMACH 4000V/B/C External Switching Characteristics (Cont.)

Over Recommended Operating Conditions

Parameter	Description <sup>1, 2, 3</sup>	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	5.0	—	7.5	—	10.0	ns
t <sub>PD_MC</sub>	20-PT combinatorial propagation delay through macrocell	—	5.5	—	8.0	—	10.5	ns
t <sub>S</sub>	GLB register setup time before clock	3.0	—	4.5	—	5.5	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	3.2	—	4.7	—	5.5	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	1.2	—	1.7	—	1.7	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	2.2	—	2.7	—	2.7	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.0	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	3.4	—	4.5	—	6.0	ns
t <sub>R</sub>	External reset pin to output delay	—	6.3	—	9.0	—	10.5	ns
t <sub>RW</sub>	External reset pulse duration	2.0	—	4.0	—	4.0	—	ns
t <sub>P<sub>TOE/DIS</sub></sub>	Input to output local product term output enable/disable	—	7.0	—	9.0	—	10.5	ns
t <sub>G<sub>P<sub>TOE/DIS</sub></sub></sub>	Input to output global product term output enable/disable	—	9.0	—	10.3	—	12.0	ns
t <sub>G<sub>OE/DIS</sub></sub>	Global OE input to output enable/disable	—	5.0	—	7.0	—	8.0	ns
t <sub>CW</sub>	Global clock width, high or low	2.2	—	2.8	—	4.0	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	2.2	—	2.8	—	4.0	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	2.2	—	2.8	—	4.0	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	227	—	168	—	125	MHz
f <sub>MAX</sub> (Ext.)	Clock frequency with external feedback, [1/ (t <sub>S</sub> + t <sub>CO</sub> )]	—	156	—	111	—	86	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.



## ispMACH 4000Z External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description <sup>1, 2, 3</sup>	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	3.5	—	3.7	—	4.2	ns
t <sub>PD_MC</sub>	20-PT combinatorial propagation delay through macrocell	—	4.4	—	4.7	—	5.7	ns
t <sub>S</sub>	GLB register setup time before clock	2.2	—	2.5	—	2.7	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	2.4	—	2.7	—	2.9	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	1.0	—	1.1	—	1.3	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	2.0	—	2.1	—	2.6	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.3	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	3.0	—	3.2	—	3.5	ns
t <sub>R</sub>	External reset pin to output delay	—	5.0	—	6.0	—	7.3	ns
t <sub>RW</sub>	External reset pulse duration	1.5	—	1.7	—	2.0	—	ns
t <sub>P<sub>TOE/DIS</sub></sub>	Input to output local product term output enable/disable	—	7.0	—	8.0	—	8.0	ns
t <sub>G<sub>P</sub>TOE/DIS</sub>	Input to output global product term output enable/disable	—	6.5	—	7.0	—	8.0	ns
t <sub>GOE/DIS</sub>	Global OE input to output enable/disable	—	4.5	—	4.5	—	4.8	ns
t <sub>CW</sub>	Global clock width, high or low	1.0	—	1.5	—	1.8	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	1.0	—	1.5	—	1.8	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	1.0	—	1.5	—	1.8	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	267	—	250	—	220	MHz
f <sub>MAX</sub> (Ext.)	clock frequency with external feedback, [1 / (t <sub>S</sub> + t <sub>CO</sub> )]	—	192	—	175	—	161	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

## ispMACH 4000Z External Switching Characteristics (Cont.)

Over Recommended Operating Conditions

Parameter	Description <sup>1, 2, 3</sup>	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	4.5	—	5.0	—	7.5	ns
t <sub>PD_MC</sub>	20-PT combinatorial propagation delay through macrocell	—	5.8	—	6.0	—	8.0	ns
t <sub>S</sub>	GLB register setup time before clock	2.9	—	3.0	—	4.5	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	3.1	—	3.2	—	4.7	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	1.3	—	1.3	—	1.4	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	2.6	—	2.6	—	2.7	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	1.3	—	1.3	—	1.3	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	3.8	—	4.2	—	4.5	ns
t <sub>R</sub>	External reset pin to output delay	—	7.5	—	7.5	—	9.0	ns
t <sub>RW</sub>	External reset pulse duration	2.0	—	2.0	—	4.0	—	ns
t <sub>P<sub>TOE/DIS</sub></sub>	Input to output local product term output enable/disable	—	8.2	—	8.5	—	9.0	ns
t <sub>G<sub>P</sub>TOE/DIS</sub>	Input to output global product term output enable/disable	—	10.0	—	10.0	—	10.5	ns
t <sub>G<sub>O</sub>E/DIS</sub>	Global OE input to output enable/disable	—	5.5	—	6.0	—	7.0	ns
t <sub>CW</sub>	Global clock width, high or low	1.8	—	2.0	—	2.8	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.0	—	2.8	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	1.8	—	2.0	—	2.8	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	200	—	200	—	168	MHz
f <sub>MAX</sub> (Ext.)	clock frequency with external feedback, [1 / (t <sub>S</sub> + t <sub>CO</sub> )]	—	150	—	139	—	111	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.